

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor substrate having a first region and a second region; a plurality of first sub-external terminals disposed on the first region;

5 a plurality of second sub-external terminals composed of terminals to be grounded and terminals to be connected to a power source; a plurality of second external terminals disposed on the second region; a first sub-wiring structure provided on the first region for electrically connecting the plurality of first

10 sub-external terminals and a plurality of circuit element connecting pads; a second sub-wiring structure for electrically connecting the plurality of second sub-external terminals and the plurality of circuit element connecting pads; and a plurality of second wiring structures provided from the first region to

15 the second region for electrically connecting the plurality of second external terminals and the plurality of circuit element connecting pads.